

**G3018K**

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

BVDSS	30V
RDS(ON)	8Ω
ID	640mA

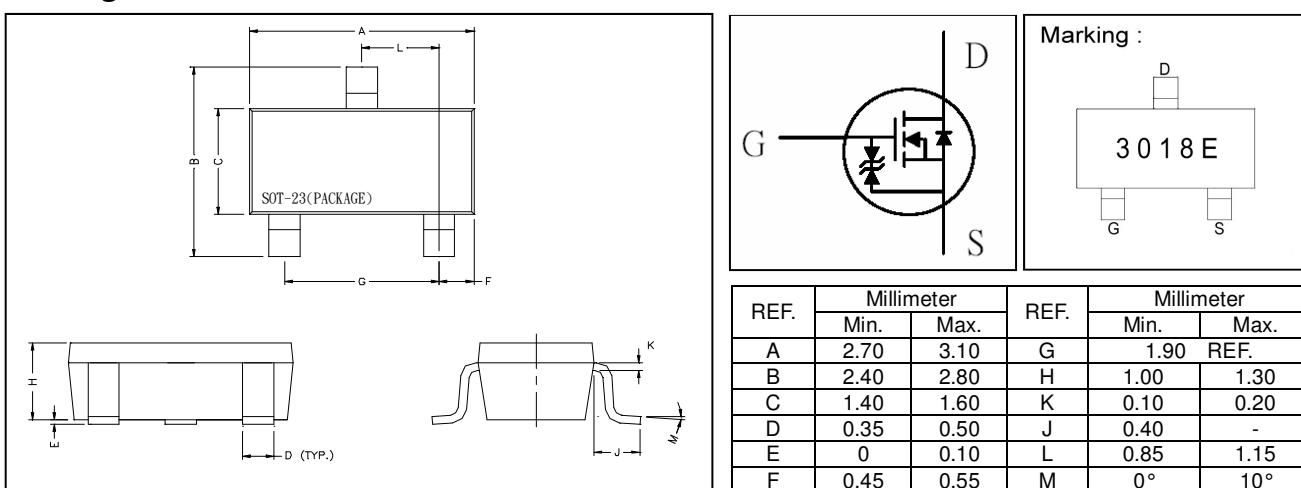
**Description**

The G3018K utilized advanced processing techniques to achieve the lowest possible on-resistance, extremely efficient and cost-effectiveness device.

The G3018K is universally used for all commercial-industrial applications.

**Features**

- \*Simple Drive Requirement
- \*Small Package Outline
- \*RoHS Compliant

**Package Dimensions****Absolute Maximum Ratings**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current <sup>3</sup> , $V_{GS}@10V$	$I_D @ T_A=25^\circ C$	640	mA
Continuous Drain Current <sup>3</sup> , $V_{GS}@10V$	$I_D @ T_A=70^\circ C$	500	mA
Pulsed Drain Current <sup>1,2</sup>	$I_{DM}$	950	mA
Power Dissipation	$P_D @ T_A=25^\circ C$	1.38	W
Linear Derating Factor		0.01	$W/\text{}^\circ C$
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 ~ +150	°C

**Thermal Data**

Parameter	Symbol	Ratings	Unit
Thermal Resistance Junction-ambient <sup>3</sup> Max.	$R_{thj-a}$	90	°C/W

## Electrical Characteristics ( $T_j = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	30	-	-	V	$\text{V}_{\text{GS}}=0$ , $\text{I}_D=250\mu\text{A}$
Breakdown Voltage Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}} / \Delta T_j$	-	0.06	-	V/ $^\circ\text{C}$	Reference to $25^\circ\text{C}$ , $\text{I}_D=1\text{mA}$
Gate Threshold Voltage	$\text{V}_{\text{GS}(\text{th})}$	0.5	-	2.0	V	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}$ , $\text{I}_D=250\mu\text{A}$
Forward Transconductance	$\text{g}_{\text{fs}}$	-	600	-	mS	$\text{V}_{\text{DS}}=10\text{V}$ , $\text{I}_D=600\text{mA}$
Gate-Source Leakage Current	$\text{I}_{\text{GSS}}$	-	-	$\pm 10$	$\mu\text{A}$	$\text{V}_{\text{GS}}= \pm 20\text{V}$
Drain-Source Leakage Current( $T_j=25^\circ\text{C}$ )	$\text{I}_{\text{DSS}}$	-	-	1	$\mu\text{A}$	$\text{V}_{\text{DS}}=30\text{V}$ , $\text{V}_{\text{GS}}=0$
Drain-Source Leakage Current( $T_j=70^\circ\text{C}$ )		-	-	100	$\mu\text{A}$	$\text{V}_{\text{DS}}=24\text{V}$ , $\text{V}_{\text{GS}}=0$
Static Drain-Source On-Resistance	$\text{R}_{\text{DS}(\text{ON})}$	-	-	8	$\Omega$	$\text{V}_{\text{GS}}=4\text{V}$ , $\text{I}_D=10\text{mA}$
		-	-	13		$\text{V}_{\text{GS}}=2.5\text{V}$ , $\text{I}_D=1\text{mA}$
Total Gate Charge <sup>2</sup>	$\text{Q}_g$	-	1	1.6	nC	$\text{I}_D=600\text{mA}$ $\text{V}_{\text{DS}}=50\text{V}$ $\text{V}_{\text{GS}}=4.5\text{V}$
Gate-Source Charge	$\text{Q}_{\text{gs}}$	-	0.5	-		
Gate-Drain ("Miller") Change	$\text{Q}_{\text{gd}}$	-	0.5	-		
Turn-on Delay Time <sup>2</sup>	$\text{T}_{\text{d}(\text{on})}$	-	12	-	ns	$\text{V}_{\text{DS}}=30\text{V}$ $\text{I}_D=600\text{mA}$ $\text{V}_{\text{GS}}=10\text{V}$ $\text{R}_G=3.3\Omega$ $\text{R}_D=52\Omega$
Rise Time	$\text{T}_r$	-	10	-		
Turn-off Delay Time	$\text{T}_{\text{d}(\text{off})}$	-	56	-		
Fall Time	$\text{T}_f$	-	29	-		
Input Capacitance	$\text{C}_{\text{iss}}$	-	32	50	pF	$\text{V}_{\text{GS}}=0\text{V}$ $\text{V}_{\text{DS}}=25\text{V}$ $f=1.0\text{MHz}$
Output Capacitance	$\text{C}_{\text{oss}}$	-	8	-		
Reverse Transfer Capacitance	$\text{C}_{\text{rss}}$	-	6	-		

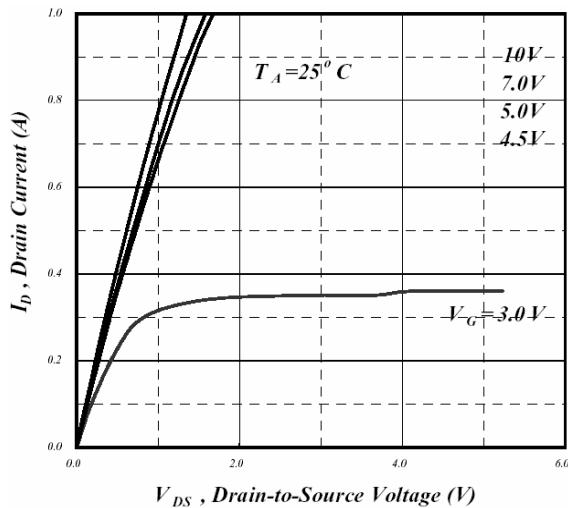
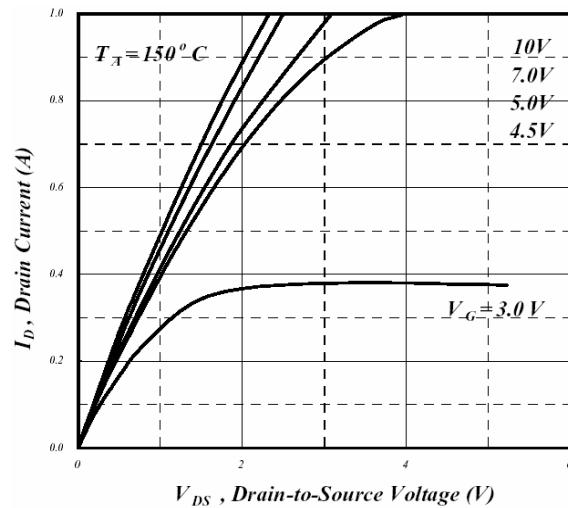
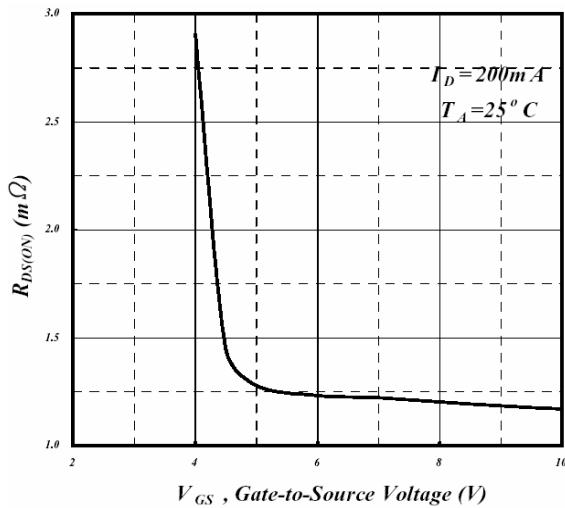
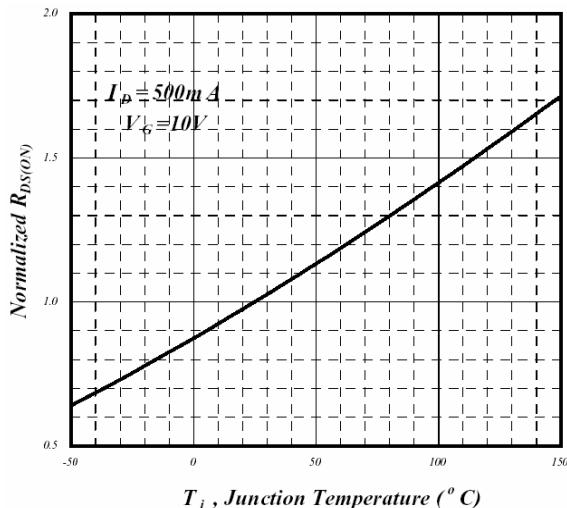
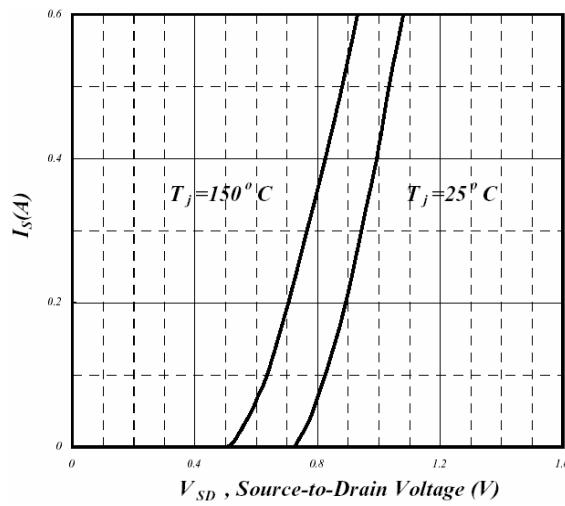
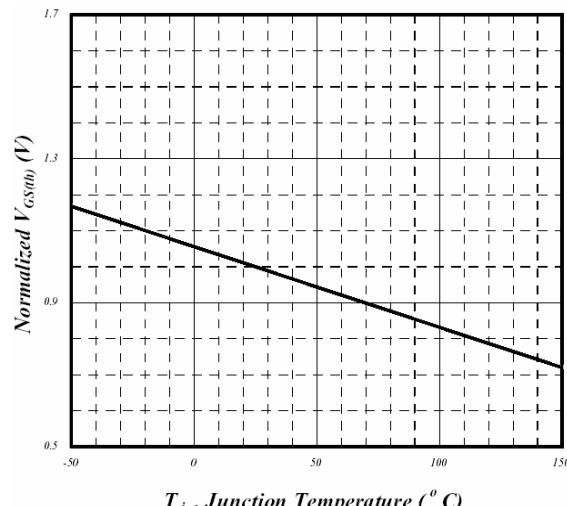
### Source-Drain Diode

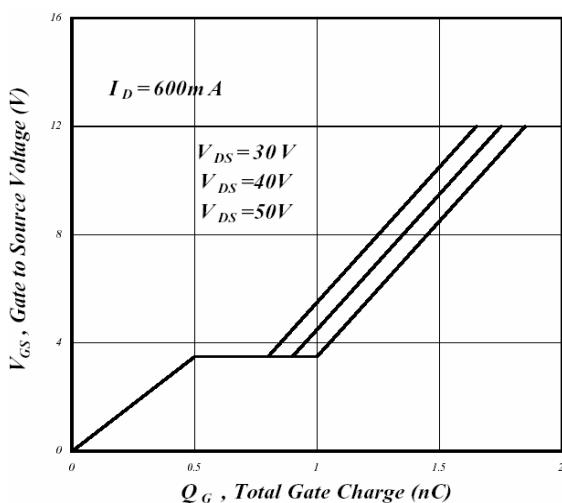
Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Forward On Voltage <sup>2</sup>	$\text{V}_{\text{SD}}$	-	-	1.2	V	$\text{I}_S=1.2\text{A}$ , $\text{V}_{\text{GS}}=0\text{V}$

Notes: 1. Pulse width limited by Max. junction temperature.

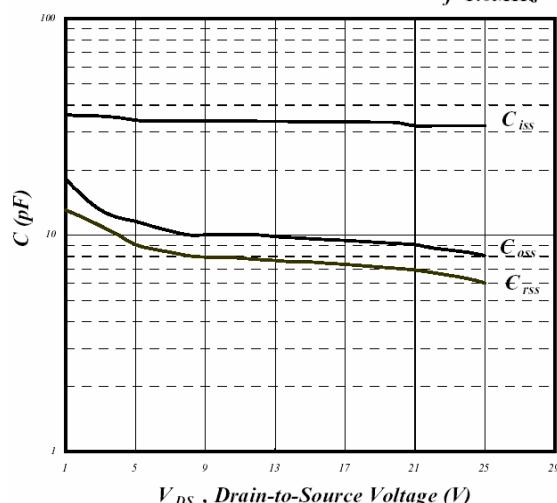
2. Pulse width  $\leq 300\text{us}$ , duty cycle  $\leq 2\%$ .

3. Surface mounted on 1 in<sup>2</sup> copper pad of FR4 board;  $270^\circ\text{C}/\text{W}$  when mounted on Min. copper pad.

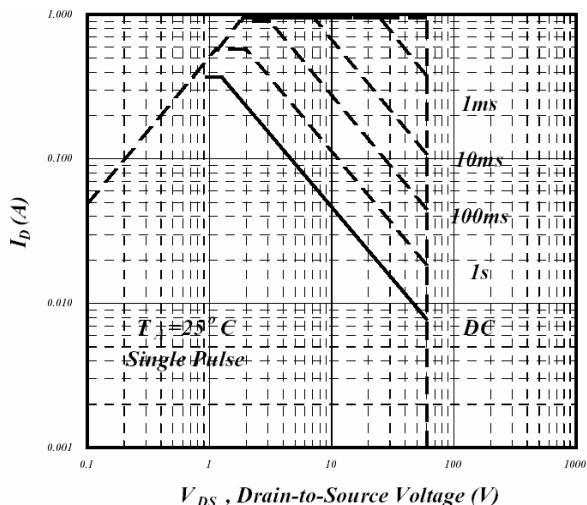
**Characteristics Curve****Fig 1. Typical Output Characteristics****Fig 2. Typical Output Characteristics****Fig 3. On-Resistance v.s. Gate Voltage****Fig 4. Normalized On-Resistance v.s. Junction Temperature****Fig 5. Forward Characteristics of Reverse Diode****Fig 6. Gate Threshold Voltage v.s. Junction Temperature**



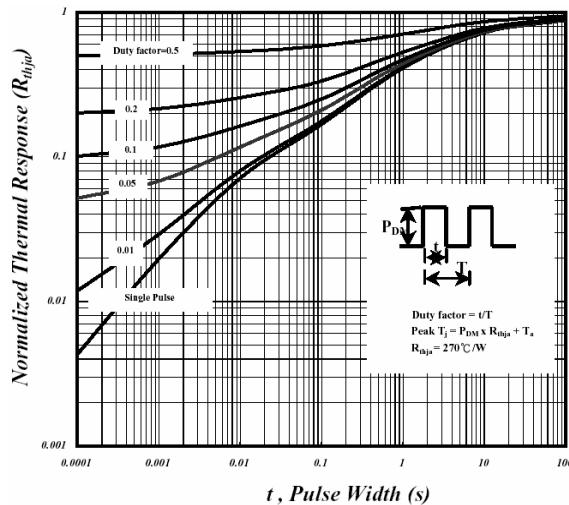
**Fig 7. Gate Charge Characteristics**



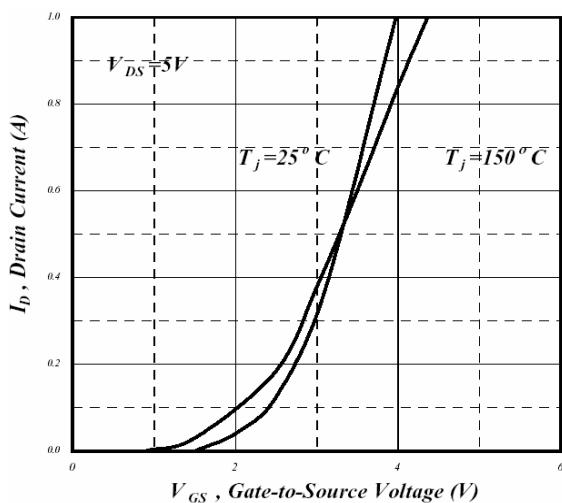
**Fig 8. Typical Capacitance Characteristics**



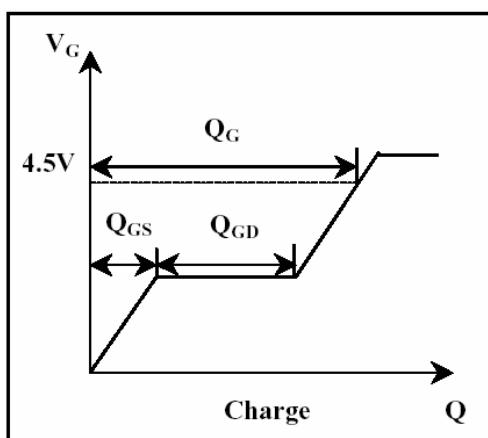
**Fig 9. Maximum Safe Operating Area**



**Fig 10. Effective Transient Thermal Impedance**



**Fig 11. Transfer Characteristics**



**Fig 12. Gate Charge Waveform**

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